EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	15	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and heating with temperature same recrystallization	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 10:47
L2	0	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (heating and healing) with temperature same recrystallization	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 10:48
L3	0	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (heating and healing) with temperature same (internal adj2 (stress strain))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 10:48
L4	0	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (heating and healing) with temperature and (internal adj2 (stress strain))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 10:48
L5	35	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (heating annealing) same (internal adj2 (stress strain))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 10:49

L6	6	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (heating annealing) same (internal adj2 (stress strain)) same recrystallization	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 10:49
L7	7	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (heating annealing) same (internal adj2 (stress strain)) and recrystallization	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 10:53
L8	35	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (heating annealing) same (internal adj2 (stress strain))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 10:53
L9	6	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (heating annealing) same (internal adj2 (stress strain)) with temperature	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 10:53
L10	35	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (heating annealing) same (internal adj2 (stress strain)) and (copper nickel)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 10:55

L11	24	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and temperature same (heating annealing) same (internal adj2 (stress strain)) and (copper nickel)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 10:55
L12	8	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and temperature same (heating annealing) with (internal adj2 (stress strain)) and (copper nickel)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 10:56
L13	33	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and temperature same (heating annealing) with (recrystallization internal adj2 (stress strain)) and (copper nickel)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 10:57
L14	25	13 not 12	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 10:57
L15	59	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and temperature same (heating annealing) same (recrystallization internal adj2 (stress strain)) and (copper nickel)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 11:02

L16	26	15 not 13	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/01 11:02
S1	5	("20030022492" | "5647968" | "6967163").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 10:46
S2	43755	("205"/$.ccls. "204"/$. ccls.) and (electrolytic electrochemic$4 electrodeposit$5 electroplat$5)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 10:48
S3	24	("205"/67-79.ccls.) and (drum wheel) and (dielectric resin) near5 (sheet film)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 10:49
S4	29	("205"/67-79.ccls.) and (drum wheel) and (dielectric adhesive resin) near5 (sheet film)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 10:54
S5	5	S4 not S3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 10:54
S6	6	("205"/67-79.ccls.) and (drum wheel) and (insulating resin nonconductive) near5 mask$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 10:55
S7	8	("205"/67-79.ccls.) and (drum wheel) and (insulating resin non $1conductive) near5 mask$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 10:57
S8	2	S7 not S6	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 10:57
S9	1	("205"/67-79.ccls.) and (drum wheel) with mask$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 10:58

S10	6	("205"/67-79.ccls.) and (drum wheel) same mask$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 10:58
S11	3	("205"/67-79.ccls.) and (drum wheel) and capacitor	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 10:58
S12	46	("3414487" | "3674656" | "3799847" | "3984598").PN. OR ("4053370").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/06/30 11:04
S13	10	("3414487" | "3998601" | "4053370").PN. OR ("4462873").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/06/30 11:11
S14	18	("3414487").URPN.	USPAT	OR	ON	2009/06/30 11:12
S15	33	("3247573" | "3414487" | "3798059" | "4586976" | "4604160" | "4753694" | "5063658" | "5233157" | "5354205" | "5358604" | "5470412" | "5480503").PN. OR ("5647966").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/06/30 11:16
S16	39	("205"/$.ccls. "204"/$. ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (graphite diamond) near7 mask$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 11:31
S17	75	("205"/$.ccls. "204"/$. ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (carbon) near7 mask$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 11:35

S18	45	("205"/$.ccls. "204"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (carbon) near4 mask$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 11:36
S19	20	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (carbon) near4 mask$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 11:37
S20	518	(electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (graphite diamond) near7 mask$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 11:41
S21	447	(electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (graphite diamond) near5 mask$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 11:41
S22	15	("205"/$.ccls.) and (electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (graphite diamond) near5 mask$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 11:42
S23	106	(electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) same (graphite diamond) near5 mask$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 11:44
S24	96	S23 not S22	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 11:44

S25	16	(electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) same (dlc glc) near5 mask$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 11:48
S26	523	(Green$1sheet Green adj2 sheet) and dielectric near5 (slurry curable)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 11:52
S27	35	(Green$1sheet Green adj2 sheet) and dielectric near5 (slurry curable) same (dispens $3 discharg$3 apply$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 11:52
S28	20	(Green$1sheet Green adj2 sheet) and dielectric near5 (slurry curable) same (dispens $3 discharg$3 apply$3) and heat$3 and dry$3	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 11:55
S29	6	("5294477" | "5455000" | "5476728" | "6248290" | "6337123" | "6426551").PN. OR ("6875526").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/06/30 12:01
S30	3	(electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (Green$1sheet Green adj2 sheet) and non $1conductive near5 particle	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 12:06
S31	42	(electrolytic electrochemic$4 plating electroforming electrodeposit$5 electroplat$5) and (Green$1sheet Green adj2 sheet) and (ceramic resin) near5 particle with (solution bath electrolyte)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 12:07

S32	24	(electrolytic electrochemic$4 electroforming electrodeposit$5 electroplat$5) and (Green$1sheet Green adj2 sheet) and (ceramic resin) near5 particle with (solution bath electrolyte)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 12:12
S33	19	(electrolytic electrochemic$4 electroforming electrodeposit$5 electroplat$5) and (Green$1sheet Green adj2 sheet) and (ceramic resin) near5 particle near10 (solution bath electrolyte)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 12:13
S34	5	(electrolytic electrochemic$4 electroforming electrodeposit$5 electroplat$5) same (ceramic resin) near5 particle near10 (solution bath electrolyte) and (Green $1sheet Green adj2 sheet)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 12:14
S35	26	(electrolytic electrochemic$4 electroforming electrodeposit$5 electroplat$5) same (ceramic resin) near5 particle near10 (solution bath electrolyte) and (capacitor inductor)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 12:16
S36	18	(electrolytic electrochemic$4 electroforming electrodeposit$5 electroplat$5) same (ceramic resin) near5 particle near10 (solution bath) and (capacitor inductor)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 12:16

S37	127	(electrolytic electrochemic$4 electroforming electrodeposit$5 electroplat$5) and (ceramic resin) near5 particle near10 (solution bath) and (capacitor inductor)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 12:25
S38	305	(electrolytic electrochemic$4 electroforming electrodeposit$5 electroplat$5) same (ceramic resin) near5 particle near10 (solution bath)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 12:25
S39	53	"205"/$.ccls. And (electrolytic electrochemic$4 electroforming electrodeposit$5 electroplat$5) same (ceramic resin) near5 particle near10 (solution bath)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 12:26
S40	0	(Green$1sheet Green adj2 sheet) and dielectric near5 (slurry curable) same (dispens$3 discharg$3 apply$3) same circuit	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 13:55
S41	11	(Green$1sheet Green adj2 sheet) and dielectric near5 (slurry curable) same (dispens$3 discharg$3 apply$3) and circuit	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 13:55
S42	56	(Capacitor inductor) and dielectric near5 (slurry curable) same (dispens$3 discharg$3 apply$3) and circuit	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 13:58
S43	6	(Capacitor inductor) and dielectric near5 (slurry curable) same (dispens$3 discharg$3 apply$3) same circuit	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 13:59

S44	57	dielectric near5 (slurry curable) same (dispens $3 discharg$3 apply$3) same (circuit pattern)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 13:59
S45	27	dielectric near5 (slurry curable) same (dispens $3 discharg$3 apply$3) same (circuit)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 13:59
S46	317	dielectric near5 (slurry curable) same (dispens $3 discharg$3 apply$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 14:01
S47	0	(Capacitor inductor) and dielectric near5 (slurry curable) with (dispens$3 printed discharg$3 apply$3) with ciruit	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 14:10
S48	2	(Capacitor inductor) and dielectric near5 (slurry curable) with (dispens$3 printed discharg$3 apply$3) with circuit	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 14:10
S49	29	(electrolytic electrochemic$4 electroforming electrodeposit$5 electroplat$5) and (Capacitor inductor) and dielectric near5 (slurry curable) with (dispens$3 printed discharg$3 apply$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 14:26
S50	20	("2711983" | "3215575" | "3574029" | "3642551" | "3953626" | "4008514" | "4050976" | "4082906" | "4254734" | "4269929" | "4383494" | "4401253" | "4540621" | "4586972").PN. OR ("6485591").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/06/30 14:30

S51	17	(electrolytic electrochemic$4 electroforming electrodeposit$5 electroplat$5) and (Capacitor inductor) and (ceramic dielectric) near5 (slurry curable) with (heat$3 firing)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 14:45
S52	279	(Capacitor inductor) and (ceramic dielectric) near5 (slurry curable) with (heat$3 firing)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 14:46
S53	48	(Capacitor inductor) and (ceramic dielectric) near5 (slurry curable) with (heat$3 firing) same temperature	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 14:47
S54	1137	(Capacitor inductor) and (ceramic dielectric) near5 (slurry curable) and (heat$3 firing) with temperature	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 14:54
S55	1236	(Green$1sheet Green adj2 sheet) and (ceramic dielectric) near5 (slurry curable) and (heat$3 firing) with temperature	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 14:54
S56	143	(Green$1sheet Green adj2 sheet) and (ceramic dielectric) near5 (slurry curable) same (heat$3 firing) with temperature	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 14:54
S57	125	S56 not S53	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/06/30 14:55

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